

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

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For: WAFER LEVEL METHODS FOR FABRICATING
MULTI-DICE CHIP SCALE SEMICONDUCTOR
COMPONENTS (AS AMENDED)

Attorney Docket No. 02-1500.1

**PRELIMINARY AMENDMENT
SUBMITTED WITH CONTINUING APPLICATION (DIVISION)
UNDER 37 CFR 1.53(b)**

December 8, 2003

Mail Stop Patent Application
Commissioner of Patents
PO Box 1450
Alexandria, VA 22313-1450

Sir:

This Preliminary Amendment is being filed with a continuation application (division) under 37 CFR 1.53(b). Please amend the captioned case as follows.